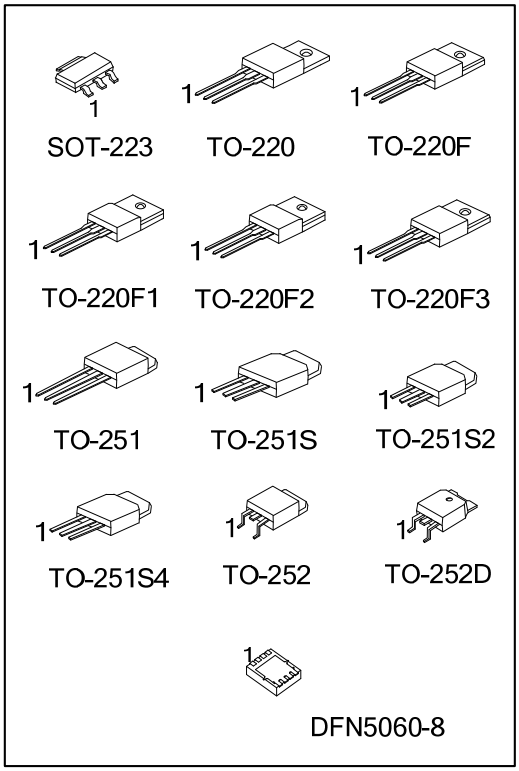
2N65-CBS

Power MOSFET

2A, 650V N-CHANNEL POWER MOSFET



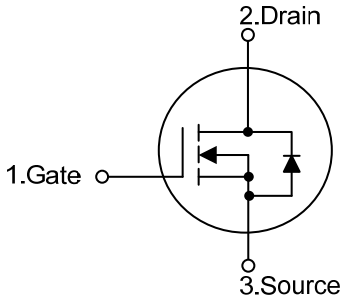
■ DESCRIPTION

The UTC **2N65-CBS** is a high voltage power MOSFET and is designed to have better characteristics, such as fast switching time, low gate charge, low on-state resistance and have a high rugged avalanche characteristics. This power MOSFET is usually used at high speed switching applications in power supplies, PWM motor controls, high efficient DC to DC converters and bridge circuits.

■ FEATURES

* $R_{DS(ON)} \leq 9.5\Omega$ @ V_{GS} = 10V, I_D =1.0A
* Fast switching capability
* Avalanche energy specified
* Improved dv/dt capability, high ruggedness

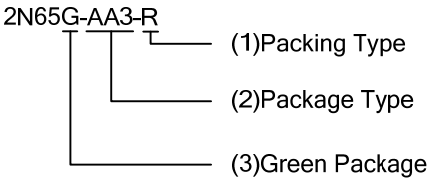
■ SYMBOL



■ ORDERING INFORMATION

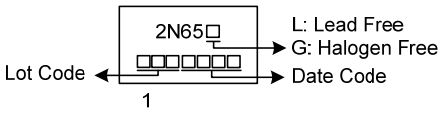
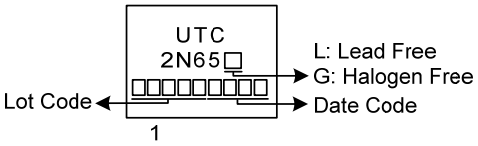
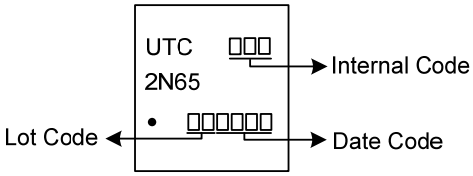
Ordering Number		Package	Pin Assignment								Packing
Lead Free	Halogen Free		1	2	3	4	5	6	7	8	
2N65G-AA3-R	2N65G-AA3-R	SOT-223	G	D	S	-	-	-	-	-	Tape Reel
2N65L-TA3-T	2N65G-TA3-T	TO-220	G	D	S	-	-	-	-	-	Tube
2N65L-TF3-T	2N65G-TF3-T	TO-220F	G	D	S	-	-	-	-	-	Tube
2N65L-TF1-T	2N65G-TF1-T	TO-220F1	G	D	S	-	-	-	-	-	Tube
2N65L-TF2-T	2N65G-TF2-T	TO-220F2	G	D	S	-	-	-	-	-	Tube
2N65L-TF3T-T	2N65G-TF3T-T	TO-220F3	G	D	S	-	-	-	-	-	Tube
2N65L-TM3-T	2N65G-TM3-T	TO-251	G	D	S	-	-	-	-	-	Tube
2N65L-TMS-T	2N65G-TMS-T	TO-251S	G	D	S	-	-	-	-	-	Tube
2N65L-TMS2-T	2N65G-TMS2-T	TO-251S2	G	D	S	-	-	-	-	-	Tube
2N65L-TMS4-T	2N65G-TMS4-T	TO-251S4	G	D	S	-	-	-	-	-	Tube
2N65L-TN3-R	2N65G-TN3-R	TO-252	G	D	S	-	-	-	-	-	Tape Reel
2N65L-TND-R	2N65G-TND-R	TO-252D	G	D	S	-	-	-	-	-	Tape Reel
2N65G-K08-5060-R	2N65G-K08-5060-R	DFN5060-8	S	S	S	G	D	D	D	D	Tape Reel

Note: Pin Assignment: G: Gate D: Drain S: Source



(1) T: Tube, R: Tape Reel
(2) AA3: SOT-223, TA3: TO-220, TF3: TO-220F, TF1: TO-220F1, TF1: TO-220F2, TF3T: TO-220F3, TM3: TO-251, TMS: TO-251S, TMS2: TO-251S2, TMS4: TO-251S4, TN3: TO-252, TND: TO-252D K08-5060: DFN5060-8
(3) G: Halogen Free and Lead Free, L: Lead Free

■ MARKING

PACKAGE	MARKING
SOT-223	
TO-220 / TO-220F TO-220F1 / TO-220F2 TO-220F3 / TO-251 TO-251S / TO-251S2 TO-251S4 / TO-252 TO-252D	
DFN5060-8	

■ ABSOLUTE MAXIMUM RATINGS (T_C=25°C, unless otherwise specified)

PARAMETER		SYMBOL	RATINGS	UNIT
Drain-Source Voltage		V_{DSS}	650	V
Gate-Source Voltage		V_{GSS}	±30	V
Avalanche Current (Note 2)		I_{AR}	1.6	A
Drain Current	Continuous	I_D	2.0	A
	Pulsed (Note 2)	I_{DM}	8.0	A
Avalanche Energy	Single Pulsed (Note 3)	E_{AS}	13	mJ
Peak Diode Recovery dv/dt (Note 4)		dv/dt	4.2	V/ns
Power Dissipation	SOT-223	P_D	3.3	W
	TO-220		54	W
	TO-220F/TO-220F1 TO-220F3		23	W
	TO-220F2		24	W
	TO-251/TO-251S TO-251S2/TO-251S4 TO-252/TO-252D		44	W
	DFN5060-8		22	W
Junction Temperature		T_J	+150	°C
Storage Temperature		T_{STG}	-55 ~ +150	°C

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged. Absolute maximum ratings are stress ratings only and functional device operation is not implied.
2. Repetitive Rating : Pulse width limited by maximum junction temperature.
3. L=10mH, I_{AS}=1.6A, V_{DD}=50V, R_G=25 Ω, Starting T_J = 25°C
4. I_{SD}≤2.0A, di/dt≤200A/μs, V_{DD} ≤ BV_{DSS}, Starting T_J = 25°C

■ THERMAL DATA

PARAMETER		SYMBOL	RATINGS	UNIT
Junction to Ambient	SOT-223	$θ_{JA}$	150	°C/W
	TO-220/TO-220F TO-220F1/ TO-220F2 TO-220F3		62.5	°C/W
	TO-251/TO-251S TO-251S2/TO-251S4 TO-252/TO-252D		100	°C/W
	DFN5060-8		75	°C/W
Junction to Case	SOT-223	$θ_{JC}$	37.8	°C/W
	TO-220		2.32	°C/W
	TO-220F/TO-220F1 TO-220F3		5.4	°C/W
	TO-220F2		5.2	°C/W
	TO-251/TO-251S TO-251S2/TO-251S4 TO-252/TO-252D		2.84 (Note)	°C/W
	DFN5060-8		5.7	°C/W

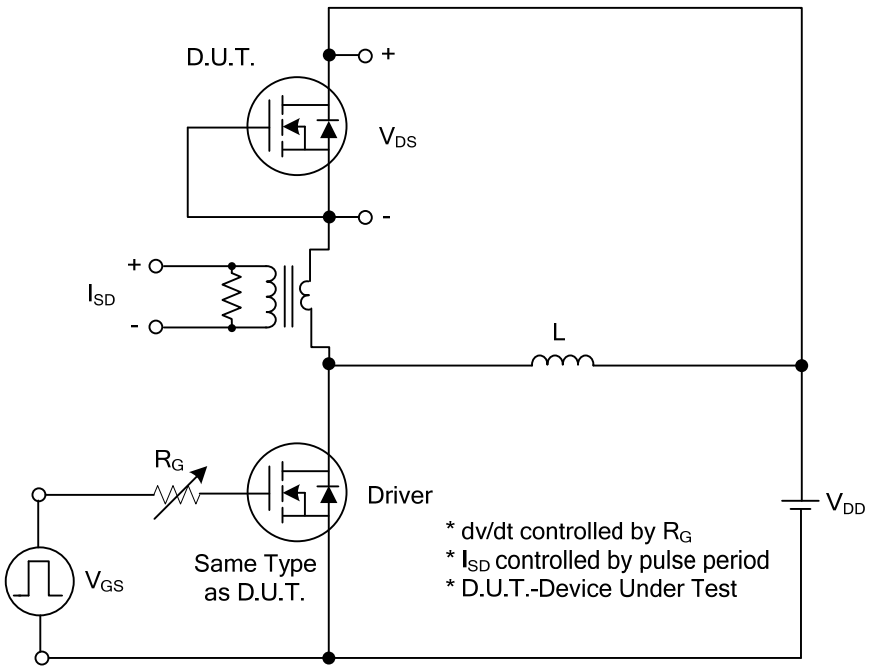
Note: The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.

■ ELECTRICAL CHARACTERISTICS (T_C =25°C, unless otherwise specified)

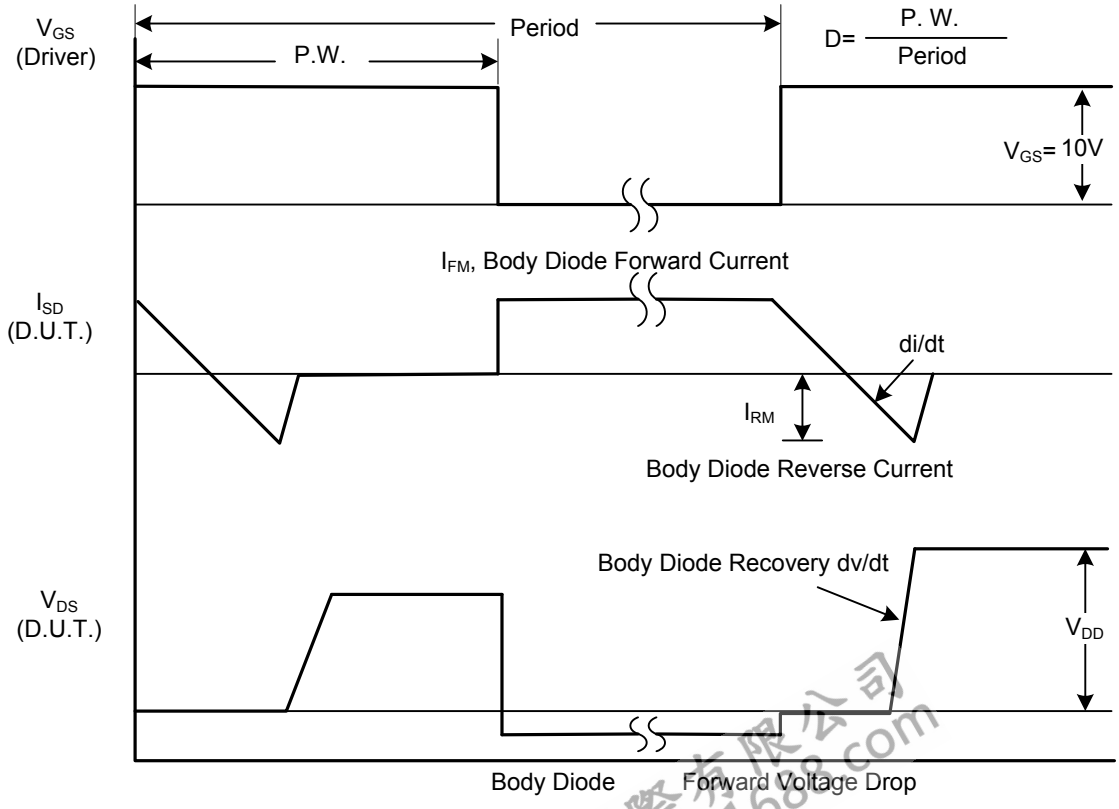
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT
OFF CHARACTERISTICS							
Drain-Source Breakdown Voltage		BV_{DSS}	V_{GS} = 0V, I_D = 250μA	650			V
Drain-Source Leakage Current		I_{DSS}	V_{DS} = 650V, V_{GS} = 0V			10	μA
Gate-Source Leakage Current	Forward	I_{GSS}	V_{GS} = 30V, V_{DS} = 0V			100	nA
	Reverse		V_{GS} = -30V, V_{DS} = 0V			-100	nA
ON CHARACTERISTICS							
Gate Threshold Voltage		$V_{GS(TH)}$	V_{DS} = V_{GS}, I_D = 250μA	2.0		4.0	V
Static Drain-Source On-State Resistance		$R_{DS(ON)}$	V_{GS} = 10V, I_D =1.0A			9.5	Ω
DYNAMIC CHARACTERISTICS							
Input Capacitance		C_{ISS}	V_{DS} =25V, V_{GS} =0V, f =1MHz		158		pF
Output Capacitance		C_{OSS}			19		pF
Reverse Transfer Capacitance		C_{RSS}			2.1		pF
SWITCHING CHARACTERISTICS							
Total Gate Charge		Q_G	V_{DS}=100V, V_{GS}=10V, I_D=2A I_G=1mA (Note 1, 2)		5		nC
Gate-Source Charge		Q_{GS}			2.6		nC
Gate-Drain Charge		Q_{GD}			0.8		nC
Turn-On Delay Time		$t_{D\ (ON)}$	V_{DS}=100V, V_{GS}=10V, I_D=2A, R_G =25Ω (Note 1, 2)		4		ns
Turn-On Rise Time		t_R			14		ns
Turn-Off Delay Time		$t_{D(OFF)}$			54		ns
Turn-Off Fall Time		t_F			34		ns
DRAIN-SOURCE DIODE CHARACTERISTICS							
Continuous Drain-Source Current		I_S				2.0	A
Pulsed Drain-Source Current		I_{SM}				8.0	A
Drain-Source Diode Forward Voltage		V_{SD}	V_{GS} = 0 V, I_{SD} = 2.0 A			1.4	V
Body Diode Reverse Recovery Time		t_{rr}	V_{GS} = 0 V, I_{SD} = 2.0 A, dI_F/dt=100A/μs		217		ns
Body Diode Reverse Recovery Charge		Q_{rr}			0.57		μC

Notes: 1. Pulse Test: Pulse width ≤ 300μs, Duty cycle≤2%.
2. Essentially independent of operating temperature.

■ TEST CIRCUITS AND WAVEFORMS

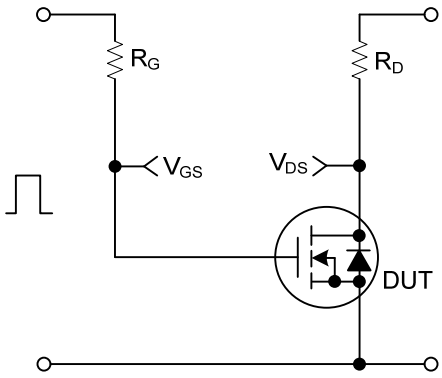


Peak Diode Recovery dv/dt Test Circuit

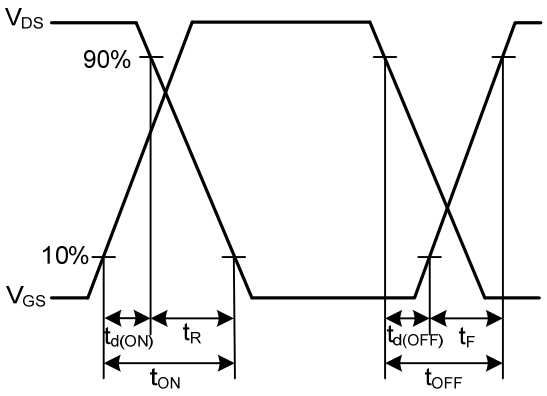


Peak Diode Recovery dv/dt Waveforms

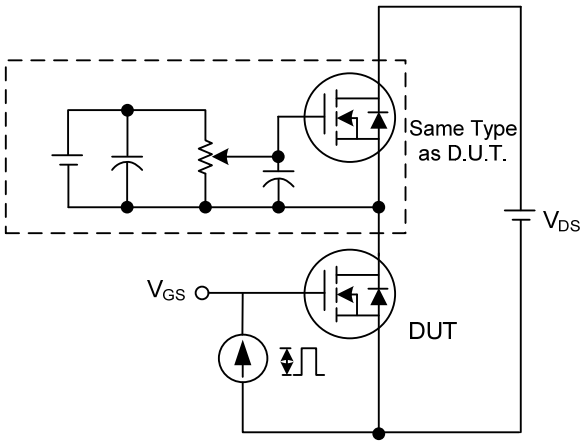
■ TEST CIRCUITS AND WAVEFORMS



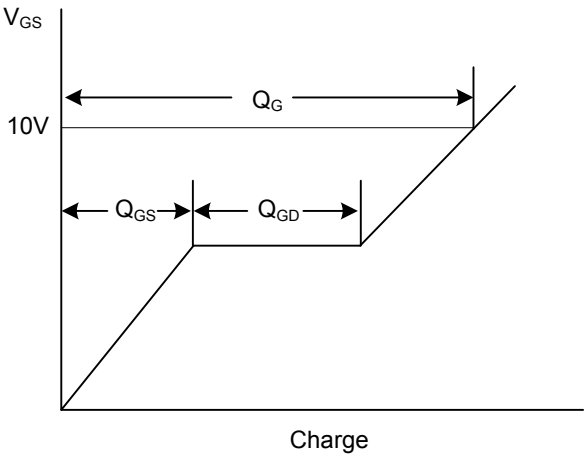
itching Test Circuit



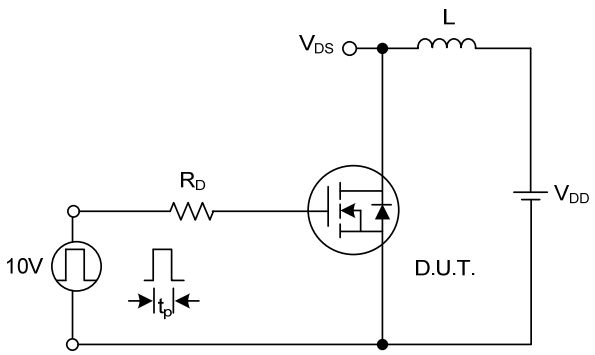
Switching Waveforms



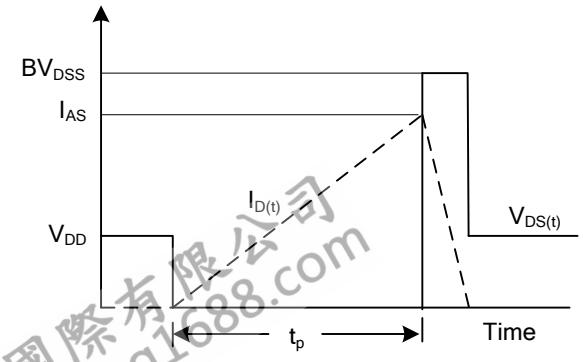
Gate Charge Test Circuit



Gate Charge Waveform



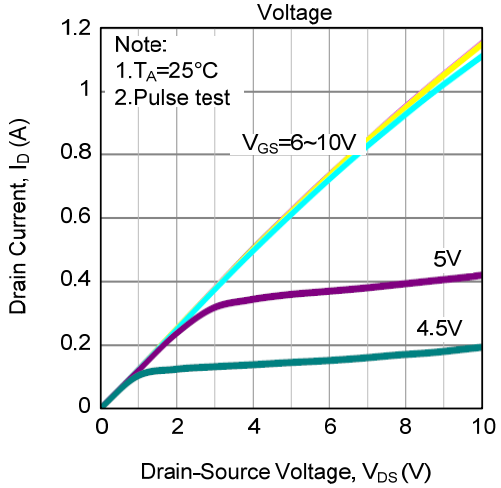
Unclamped Inductive Switching Test Circuit



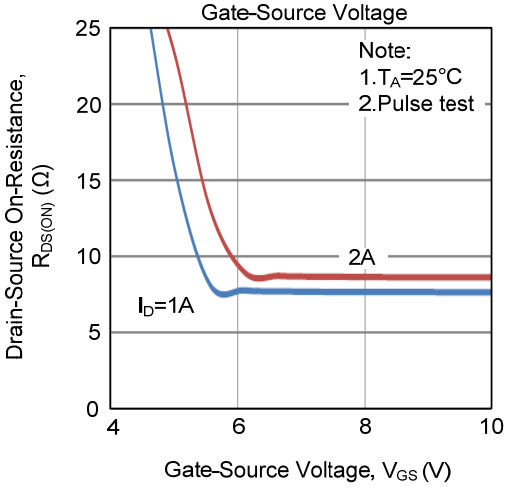
Unclamped Inductive Switching Waveforms

■ TYPICAL CHARACTERISTICS

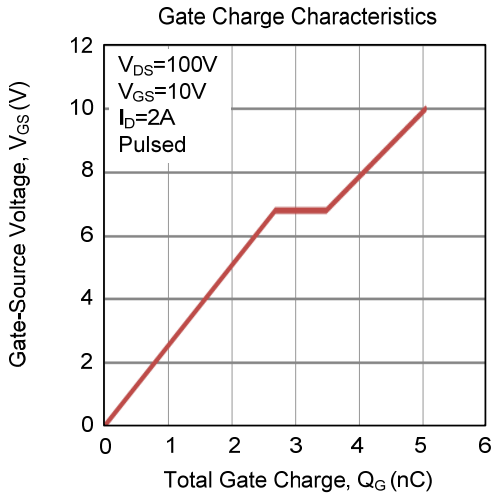
Drain Current vs. Drain-Source Voltage



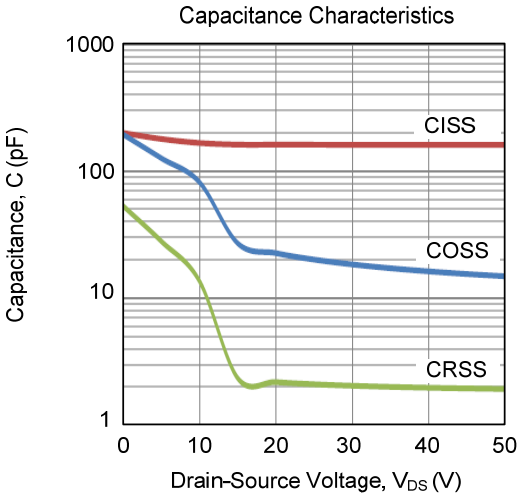
Drain-Source On-Resistance vs. Gate-Source Voltage



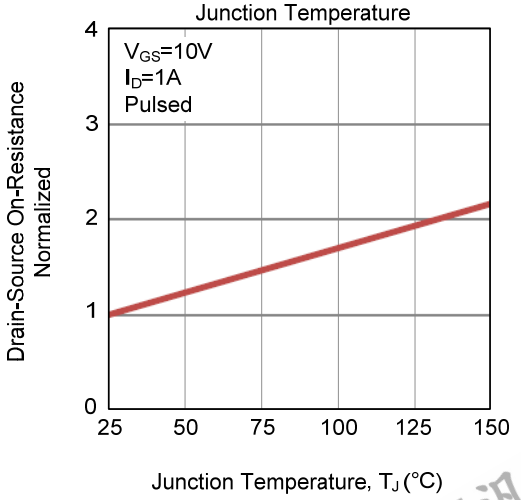
Gate Charge Characteristics



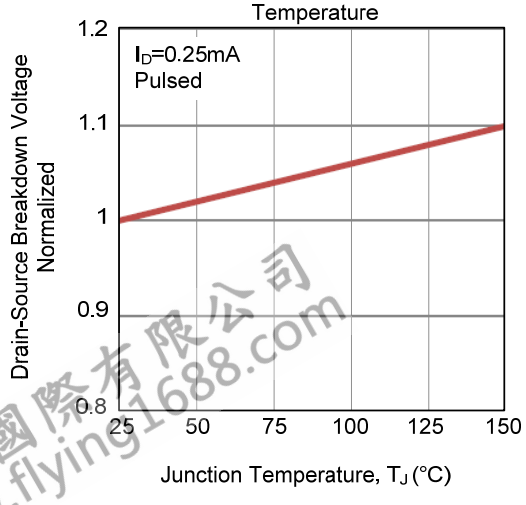
Capacitance Characteristics



Drain-Source On-Resistance vs. Junction Temperature

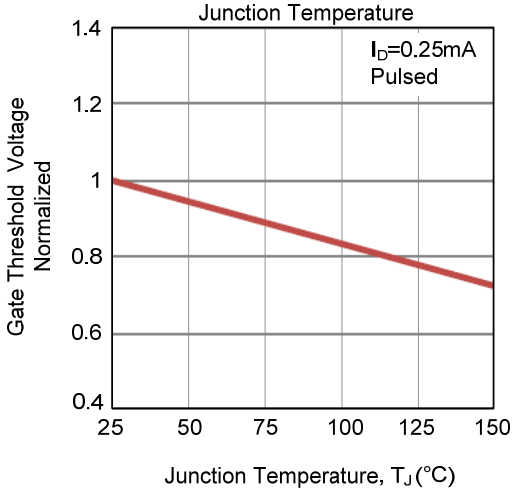


Breakdown Voltage vs. Junction Temperature

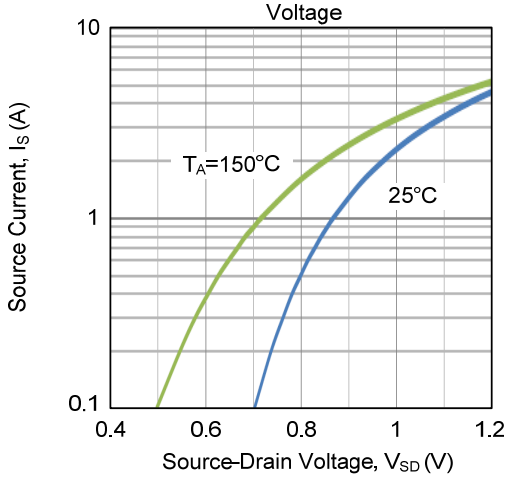


■ TYPICAL CHARACTERISTICS (Cont.)

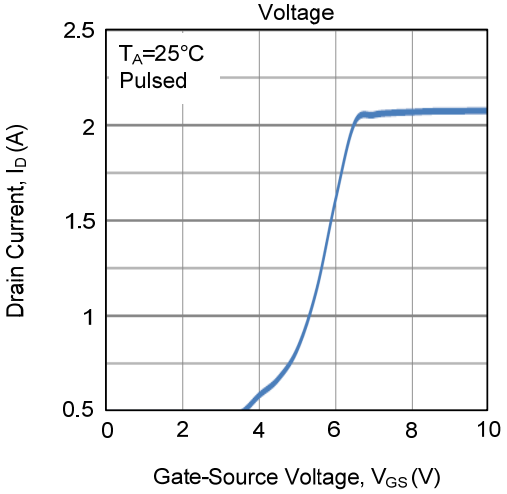
Gate Threshold Voltage vs. Junction Temperature



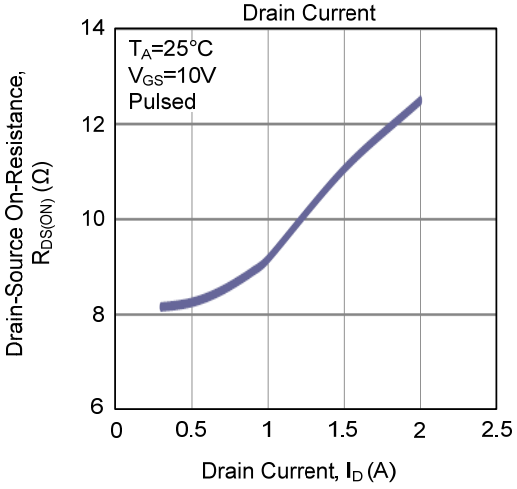
Source Current vs. Source-Drain Voltage



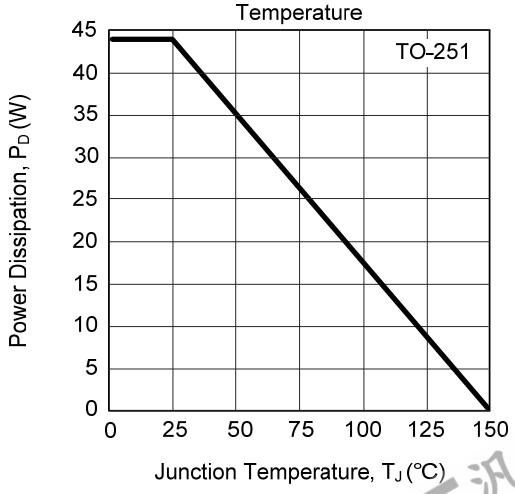
Drain Current vs. Gate-Source Voltage



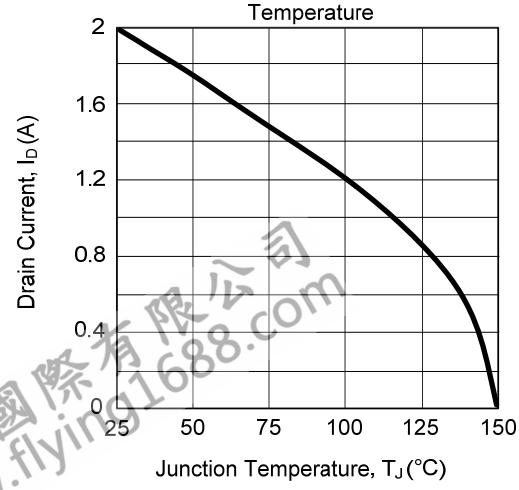
Drain-Source On-Resistance vs. Drain Current



Power Dissipation vs. Junction Temperature



Drain Current vs. Junction Temperature



■ TYPICAL CHARACTERISTICS (Cont.)